

HYBOND

Soft Touch™

MODEL 572A

DEEP ACCESS

THERMOSONIC WIRE AND RIBBON BONDER

0.5 to 2.0 mil (12.7 to 50 μm) diameter wire and
up to 1 x 10 mil (25.4 x 254 μm) ribbon



STANDARD FEATURES:

- ! HYBOND *Soft Touch™* energy system.
- ! Front panel ultrasonic test button.
- ! Deep vertical access of 0.59 in. (1,49cm).
- ! Horizontal reach of 3.5 in. (8,89cm).
- ! 0.5 and 2 inch spool mounts standard.
- ! Loop height control adjustment.
- ! Motorized vertical wire feed.
- ! 1-1-2, 1-2-2 and 1-2-1 stitch capability.
- ! Deep access wire-in-tool 90 deg. wire feed.
- ! Swing away clamps for easier wire threading.
- ! Variable angle microscope mount.
- ! Audio and visual bond fault indicators.
- ! Independent 1st and 2nd bond controls.
- ! Front panel feed switch for manual tail adjust.
- ! 6 x 8.5 inch X-Y work platform.
- ! LED display for monitoring temperature.
- ! Independent lever for Z bond head control.
- ! Wire and ribbon bonding capability.

Imitated but never duplicated, HYBOND's exclusive *Soft Touch™* force ramping system bonds effectively with less trauma to sensitive materials like GaAs and InP. Superior wire control is provided by the motorized feed system which features clamps capable of feeding wire and ribbon, dial adjustable tail length, switch for manual tail length adjustment and clamp pull back dial adjustment to allow bonding and cutting of softer (higher elongation) wires than conventionally used for wedge bonding. Model 572A includes front panel independent controls for 1st and 2nd bond U/S, Time & Force as well as for the built in workstage temperature controller. The 572A has a proven track record of safe and effective wire and ribbon bonding worldwide.

Partial List of Available Options:

- ! OP-06S6 Leica Stereo Zoom Microscope.
- ! OP-06A Nikon SMZ-660 Microscope.
- ! OP-08A Dual Fiber Optic Illuminator.
- ! OP-12 240VAC 50/60Hz Input Wiring.
- ! OP-30 8:1 X-Y Manipulator.

- ! OP-31 Tool Heater and Temp.Controller.
- ! OP-44 High/Low U/S Power Selector.
- ! OP-83 Heated Transducer for Tool Heat.
- ! WST-15A Heated Workstage, 2.125 in. Top.
- ! WST-19B Heated Workstage, 4 x 4 in. Top.

Specifications for Model 572A:

- ! Ultrasonic (U/S) System: PLL self tuning.62.5KHz (nominal) system (± 2.5 KHz).
- ! U/S Power Range: 0-1 Watt on low (default) setting and 0-2 Watts on high setting.
- ! Bond Time Range: 10mSec. to 150mSec.
- ! Bond Force Range: 15gr. to 150gr.
- ! Temperature control Range: Ambient to 250 degrees Celsius.
- ! Bondable Wire Diameters: 0.5 to 2.0 mil (12,7 to 50 μ m) diameter.
- ! Bondable Ribbon Dimensions: Up to 1x10mil (25,4 x 254 μ m).
- ! Bondable Wire/Ribbon Materials: Gold and aluminum.
- ! Bond head movement: Manual
- ! Bond actuation: Switch at fixed height. Activated by lever.
- ! Z Travel/Vertical Bonding Window: 0.5in. (1,27cm)/60-100mils (152-254 μ m)
- ! Table Motion: 4:1, manual.
- ! Input Power Requirements: 110 VAC 50/60Hz @ 10A max. For 240VAC bonder must have OP-12
- ! Minimum Bench Space Required: 20.0 x 20.0 in. (50,8 x 50,8cm).
- ! Unit Weight/Shipping Weight: 55lbs (24,9Kg)/135lbs (61.4Kg). Shipping weight may vary.
- ! Industry Standards: CE.



For more information, contact:

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